

## Package Material Composition and Mass Calculation

Customer: PLX TECHNOLOGY INC.  
 Package: PBGA 256L  
 Device Type: PCI9056-BA66BI G  
 Body Size: 17 X 17  
 Die Size: 176 X 171

Date: 28/2/2005

|               | name       | composition     | %          | mg.(ave) | mg.          | %            | PPM            |
|---------------|------------|-----------------|------------|----------|--------------|--------------|----------------|
| Mold Compound | KE-G1250   |                 |            |          | <u>327.1</u> | <u>46.58</u> | <u>465.822</u> |
|               |            | Silica Fused    | 60676-86-0 | 84 ~ 92  | 287.85       | 40.99        | 409,923        |
|               |            | Epoxy Resin     |            | 5 ~ 9    | 19.63        | 2.79         | 27,949         |
|               |            | Phenolic Resin  |            | 4 ~ 8    | 16.36        | 2.33         | 23,291         |
|               |            | Other           |            | <1       | 3.27         |              |                |
| Die Attach    | AB 2000B   |                 |            |          | <u>1.7</u>   | <u>0.24</u>  | <u>2,421</u>   |
|               |            | Silver          | 7440-22-4  | 70~90    | 1.19         | 0.17         | 1,695          |
|               |            | Epoxy Resin     |            | 1~10     | 0.085        | 0.01         | 121            |
|               |            | Diester         |            | 5~20     | 0.17         | 0.02         | 242            |
|               |            | Polymeric Resin |            | 1~10     | 0.085        |              |                |
|               |            | Ester           |            | 5~20     | 0.17         |              |                |
| Substrate     |            |                 |            |          | <u>193.0</u> | <u>27.49</u> | <u>274.850</u> |
|               |            | Copper          | 7440-50-8  | 30       | 57.90        | 8.25         | 82,455         |
|               |            | PSR-4000 AUS 5  | 64742-94-5 | 4.3      | 8.30         | 1.18         | 11,819         |
|               |            | Nickel          | 7440-02-0  | 4.2      | 8.11         | 1.15         | 11,544         |
|               |            | Gold            | 7440-57-5  | 0.5      | 0.97         | 0.14         | 1,374          |
|               |            | BT              | 75-21-8    | 57.4     | 110.78       |              |                |
|               |            | Epoxy Resin     | 78-85-1    | 3.6      | 6.95         |              |                |
| Die           | Silicon    | Silicon         |            |          | <u>26</u>    | <u>3.70</u>  | <u>37.026</u>  |
| Wire          | TANAKA GMH |                 |            |          | <u>8.5</u>   | <u>1.21</u>  | <u>12,105</u>  |
|               |            | Au              |            | 99.99    | 8.4992       | 1.21         | 12,104         |
|               |            | Ion Impurities  |            | 0.01     | 0.0009       | 0.00         | 1.210          |
| Solder Ball   | Sn/Ag/Cu   |                 |            |          | <u>145.9</u> | 20.78        | 207775.56      |
|               |            | Sn              |            | 96.5     | 140.79       | 20.05        | 200503.42      |
|               |            | Ag              |            | 3        | 4.38         | 0.62         | 6233.27        |
|               |            | Cu              |            | 0.5      | 0.73         | 0.10         | 1038.88        |
| Total         |            |                 |            |          | <u>702.2</u> | 100.00       | 1,000,000      |